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- Each Device Drives 32 Lines
- –120-V PNP Open-Collector Parallel Outputs
- High-Speed Serially Shifted Data Inputs
- CMOS-Compatible Inputs
- Strobe and Sustain Inputs Provided
- Serial Data Output for Cascade Operation

description

The SN751508 and SN751518 are monolithic integrated circuits designed to drive the data lines of a dc plasma panel display. The SN751518 pin sequence is reversed from the SN751508 for ease in printed-circuit-board layout.

Each device consists of two 16-bit shift registers, 32 latches, 32 OR gates, and 32 pnp opencollector output AND gates. Typically, a 32-bit data string is split into two 16-bit data strings externally and then entered in parallel into the shift registers on the high-to-low transition of the clock signal. A high LATCH ENABLE transfers the data from the shift registers to the inputs of 32 OR gates through the latches. Data present in the latch during the high-to-low transition of LATCH ENABLE is stored. When STROBE is high, the latch is masked and a high is placed on the data input of the output AND gates. When STROBE is low and SUSTAIN is high, data from the latches is reflected at the outputs. When low, SUSTAIN forces all outputs to their off state. Drivers can be cascaded via the serial data outputs of the static shift registers. These outputs are not affected by LATCH ENABLE, STROBE, or SUSTAIN.

The SN751508 and the SN751518 are characterized from 0°C to 70°C.

SN751508 FT PACKAGE (TOP VIEW)								
Q32 Q31 Q30 Q29 Q28 Q27 Q26 Q25 Q24 Q23 Q22 Q21 Q20 Q19 Q19 Q18 Q17 GND NC STROBE NC CLOCK V _{CC} SERIAL OUT2 SERIAL OUT1	$\begin{array}{c}1\\1\\2\\4\\5\\6\\7\\8\\9\\10\\11\\12\\13\\14\\15\\16\\17\\18\\9\\20\\21\\22\\23\\24\end{array}$	48 47 46 45 44 43 42 41 40 39 38 37 36 35 34 33 32 31 30 29 28 27 26 25	Q1 Q2 Q3 Q4 Q5 Q6 Q7 Q8 Q9 Q10 Q11 Q12 Q13 Q14 Q15 Q16 GND SUSTAIN NC LATCH ENABLE NC V _{CC} DATA IN2 DATA IN1					
SN75151 (8 TOP	. FT P VIEW	ACKAGE /)					
Q1 Q2 Q3 Q4 Q5 Q5 Q5 Q7 Q7 Q8 Q10 Q11 Q11 Q12 Q13 Q14 Q14 Q15 Q14 Q15 Q16 SUSTAIN SUSTAIN NC LATCH ENABLE NC LATCH ENABLE NC DATA IN2	1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	48 47 46 45 44 43 42 41 40 39 38 37 36 35 34 33 32 31 30 29 28 27 26 25	Q32 Q31 Q30 Q29 Q28 Q27 Q26 Q25 Q24 Q23 Q22 Q21 Q20 Q19 Q19 Q19 Q18 Q17 GND NC STROBE NC STROBE NC CLOCK V _{CC} SERIAL OUT2 SERIAL OUT2					

NC - No internal connection

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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logic symbols[†]



[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagram (positive logic)



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FUNCTION TABLE										
FUNCTION	CONTROL INPUTS				LATCHES	OUTPUTS				
	CLOCK	LATCH	STROPE		R1 THRU R32	LC1 THRU	SERIAL		01 THPU 032	
	CLOCK	ENABLE	STROBE	3031AIN		LC32		S02		
Load	$\stackrel{\downarrow}{No}\downarrow$	X X	X X	X X	Load and shift [†] No change	Determined by LATCH ENABLE [‡]	R31	R32	Determined by SUSTAIN and STROBE	
Latch Enable	X X	L H	X X	X X	As determined above	Stored data New data	R31	R32	Determined by SUSTAIN and STROBE	
Strobe	x x	X X	L H	H H	As determined above	Determined by LATCH ENABLE [‡]	R31	R32	LC1 thru LC32 All on (high)	
Sustain	x	Х	Х	L	As determined above	Determined by LATCH ENABLE [‡]	R31	R32	All off	

H = high level, L = low level, X = irrelevant, \downarrow = high-to-low transition

[†] Each even-numbered shift register stage takes on the state of the next-lower even-numbered stage, and likewise each odd-numbered shift register stage takes on the state of the next-lower odd-numbered stage; i.e., R32 takes on the state of R30, R30 takes on the state of R28, ... R4 takes on the state of R2, R2 takes on the state of DATA IN2, R31 takes on the state of R29, R29 takes on the state of R27, ... R3 takes on the state of R1, and R1 takes on the state on DATA IN1.

[‡]New data enters the latches while LATCH ENABLE is high. This data is stored while LATCH ENABLE is low.

typical operating sequence





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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC} (see Note 1)	\ldots -0.4 to 7 V
On-state Q output voltage range, VO –	120 V to V _{CC} + 0.4 V
Input voltage range, V ₁	-0.4 V to V _{CC} + 0.4 V
Serial output voltage range	-0.4 V to V _{CC} + 0.4 V
Continuous total power dissipation at (or below) 25°C free-air temperature (see Note 2)) 1025 mW
Operating free-air temperature range, T _A	\ldots . 0°C to 70°C
Storage temperature range	$\dots -65^{\circ}C$ to $150^{\circ}C$
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

NOTES: 1. Voltages values are with respect to GND.

2. For operation above 25°C free-air temperature, derate linearly to 656 mW at 70°C at the rate of 8.2 mW/°C.



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recommended operating conditions

		MIN	NOM	MAX	UNIT	
Supply voltage, V _{CC}	4.5	5	5.5	V		
Output voltage, VO				-75	V	
	$V_{CC} = 4.5 V$	3.6			v	
High-level input voltage, VIH	V _{CC} = 5.5 V	4.4				
	$V_{CC} = 4.5 V$			0.9	V	
	V _{CC} = 5.5 V			1		
Output current, $I_O (T_A = 25^{\circ}C)$				-1.2	mA	
Clock frequency, f _{clock}				5	MHz	
	CLOCK	75			ns	
	DATA IN	160				
Pulse duration, t_W (see Figure 1)	LATCH ENABLE	90				
	STROBE	2				
	SUSTAIN	2			μs	
Setup time, t _{SU} (see Figure 1)	DATA IN before CLOCK \downarrow	20				
	CLOCK low before LATCH ENABLE [↑]	50				
	LATCH ENABLE low before CLOCK \downarrow	0			ns	
	LATCH ENABLE high before STROBE \downarrow	0				
	LATCH ENABLE high before SUSTAIN↑	0				
Hold time, DATA IN after CLOCK↓, t _h (see Figure 1)					μs	
Operating free-air temperature, T _A				70	°C	

electrical characteristics over operating free-air temperature range, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT	
	High-level output voltage	Q outputs	I _{OH} = -0.5 mA		4	4.5		
VOH		SERIAL OUT 1, 2	V _{CC} = 5.5 V	I _{OH} = -100 μA	4.3	4.6		
				I _{OH} = -20 μA	4.4			V
				I _{OH} = -100 μA	3.4	3.6		
			VCC = 4.5 V	I _{OH} = -20 μA	3.6			
	Low-level output voltage	SERIAL OUT 1, 2	V _{CC} = 5.5 V	I _{OL} = 100 μA		0.9	1.2	V
VOL				I _{OL} = 20 μA			1.1	
			V _{CC} = 4.5 V	I _{OL} = 100 μA		0.9	1.1	
				I _{OL} = 20 μA			0.9	
IOH	High-level Q output current		T _A = 25°C,	$V_{O} = 3 V$	-1.2			mA
IOL	Low-level Q output current		T _A = 25°C,	$V_{O} = -75 V$			-500	μA
Iн	High-level input current		T _A = 25°C,	VI = VCC			1	μA
١ _{IL}	Low-level input current		T _A = 25°C,	V _I = 0			-1	μA
ICC	Supply current		All Q outputs high,	V _{CC} = 5.5 V		17	25	
			All Q outputs low				3	
Ci	Input capacitance						15	pF

[†] All typical values are at $T_A = 25^{\circ}C$.



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switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tpd	Propagation delay time, CLOCK to SERIAL OUT			100	150	ns
^t DLH	Delay time, low-to-high-level Q output from SUSTAIN or STROBE			0.3‡	1	μs
^t DHL	Delay time, high-to-low-level Q output from SUSTAIN or STROBE	R _L = 91 kΩ,		1‡	2.5	μs
^t TLH	Transition time, low-to-high-level Q output	See Figures 1 and 2		2	5	μs
^t THL	Transition time, high-to-low-level Q output			11	18	μs

[‡] Typical values for delay times are measured from SUSTAIN.



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PARAMETER MEASUREMENT INFORMATION

NOTE: Input t_f and t_f are less than or equal to 10 ns.

Figure 1. Input Timing and Switching Time Voltage Waveforms



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PARAMETER MEASUREMENT INFORMATION

- NOTES: A. Input pulses are supplied by generators having the following characteristics: t_W = 100 ns, PRR \leq 5 MHz, $t_f \leq$ 10 ns, $t_f \leq$ 10 ns, Z_O = 50 Ω .
 - B. CL includes probe and jig capacitance.

Figure 2. Test Circuit



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TYPICAL CHARACTERISTICS





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TYPICAL CHARACTERISTICS



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